

# ABSTRACT OF THE DISCLOSURE

A surface of an external electrode 3 of an electronic part 4 is formed with a coating containing resin ingredient. Thereby, adhesion strength and reliability may be significantly improved in mounting an electronic part onto a circuit board 1 through the medium of a conductive adhesive. Further, it will be able to mount an electronic part to an element to be mounted by utilizing a conductive adhesive forming an external electrode 3 as a connecting element.

Further, surface roughness ( $R_a$ ) of an external electrode 3 of an electronic part is set to  $0.1\text{ }\mu\text{m}$  or more and to  $10.0\text{ }\mu\text{m}$  or less and preferably to  $1.0\text{ }\mu\text{m}$  or more and to  $5.0\text{ }\mu\text{m}$  or less. Thereby, adhesion strength with a conductive adhesive may be significantly enhanced in comparison with a conventional electronic part presented.